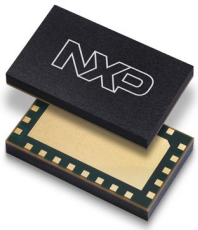
AFSC5G26E39

Airfast Power Amplifier Module

Rev. 2 — 14 June 2024

Product data sheet



1 General description

The AFSC5G26E39 is a fully integrated Doherty power amplifier module designed for wireless infrastructure applications that demand high performance in the smallest footprint. Ideal for applications in massive MIMO systems, outdoor small cells and low power remote radio heads. The field−proven LDMOS power amplifiers are designed for TDD and FDD LTE systems.

2 Typical performance

Table 1. 2496–2690 MHz — Typical LTE Performance

P_{out} = 8 W Avg., V_{DD} = 27 Vdc, 1 × 20 MHz LTE, Input Signal PAR = 8 dB @ 0.01% Probability on CCDF. (1)

Carrier Center Frequency	Gain (dB)	ACPR (dBc)	PAE (%)
2506 MHz	29.2	−26.5	40.4
2600 MHz	29.6	−28.0	41.8
2680 MHz	30.2	−26.4	41.5

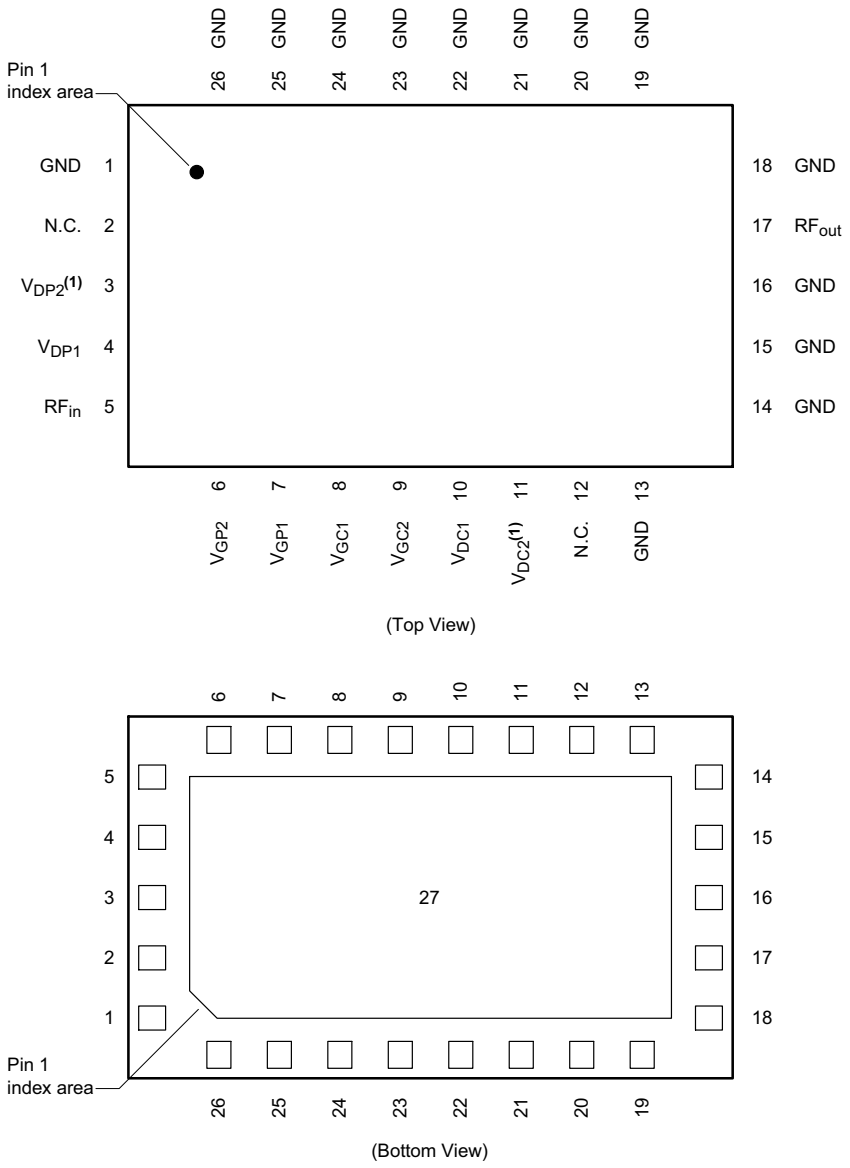
1. All data measured with device soldered in NXP reference circuit.

3 Features and benefits

- Frequency: 2496−2690 MHz
- Advanced high performance in−package Doherty
- Fully matched (50 ohm input/output, DC blocked)
- Designed for low complexity analog or digital linearization systems

4 Pinning information

4.1 Pinning



Note: Exposed backside of the package is DC and RF ground.

Figure 1. Pin Connections

1. V_{DP2} and V_{DC2} are DC coupled internal to the package and must be powered by a single DC power supply.

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4.2 Functional pin description

Table 2. Functional Pin Description

Pin Number	Pin Function	Pin Description
1, 13, 14, 15, 16, 18, 19, 20, 21, 22, 23, 24, 25, 26, 27	GND	Ground
2, 12	N.C.	No Connection
3	V_{DP2}	Peaking Drain Supply, Stage 2
4	V_{DP1}	Peaking Drain Supply, Stage 1
5	RF_{in}	RF Input
6	V_{GP2}	Peaking Gate Supply, Stage 2
7	V_{GP1}	Peaking Gate Supply, Stage 1
8	V_{GC1}	Carrier Gate Supply, Stage 1
9	V_{GC2}	Carrier Gate Supply, Stage 2
10	V_{DC1}	Carrier Drain Supply, Stage 1
11	V_{DC2}	Carrier Drain Supply, Stage 2
17	RF_{out}	RF Output

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5 Maximum ratings

Table 3. Maximum Ratings

Rating	Symbol	Value	Unit
Gate−Bias Voltage Range	V_G	−0.5 to +10	Vdc
Operating Voltage Range	V_{DD}	24 to 30	Vdc
Storage Temperature Range	T_{stg}	−65 to +150	°C
Case Operating Temperature	T_C	125	°C
Peak Input Power (2600 MHz, Pulsed CW, 10 μsec(on), 10% Duty Cycle)	P_{in}	25	dBm

6 Lifetime

Table 4. Lifetime

Characteristic	Symbol	Value	Unit
Mean Time to Failure Case Temperature 125°C, 8 W Avg., 32 Vdc	MTTF	> 10	Years

7 ESD protection characteristics

Table 5. ESD Protection Characteristics

Test Methodology	Class
Human Body Model (per JS−001−2017)	1B
Charge Device Model (per JS−002−2014)	C2a

8 Moisture sensitivity level

Table 6. Moisture Sensitivity Level

Test Methodology	Rating	Package Peak Temperature	Unit
Per JESD22−A113, IPC/JEDEC J−STD−020	3	260	°C

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9 Electrical characteristics

9.1 DC characteristics

Table 7. DC Characteristics

(T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Typ	Range	Unit
Carrier Stage 1 — On Characteristics				
Gate Threshold Voltage (1) (V_{DS} = 10 Vdc, I_D = 2.4 µAdc)	$V_{GS(th)}$	1.2	±0.4	Vdc
Gate Quiescent Voltage (V_{DS} = 27 Vdc, I_{DQ1A} = 24 mAdc)	$V_{GS(Q)}$	1.9	±0.4	Vdc
Fixture Gate Quiescent Voltage (V_{DD} = 27 Vdc, I_{DQ1A} = 24 mAdc, Measured in Functional Test)	$V_{GG(Q)}$	4.9	±1.4	Vdc
Carrier Stage 2 — On Characteristics				
Gate Threshold Voltage (1) (V_{DS} = 10 Vdc, I_D = 19 µAdc)	$V_{GS(th)}$	1.2	±0.4	Vdc
Gate Quiescent Voltage (V_{DS} = 27 Vdc, I_{DQ2A} = 65 mAdc)	$V_{GS(Q)}$	1.8	±0.4	Vdc
Fixture Gate Quiescent Voltage (V_{DD} = 27 Vdc, I_{DQ2A} = 65 mAdc, Measured in Functional Test)	$V_{GG(Q)}$	2.7	±1.2	Vdc
Peaking Stage 1 — On Characteristics (1)				
Gate Threshold Voltage (V_{DS} = 10 Vdc, I_D = 4.4 µAdc)	$V_{GS(th)}$	1.2	±0.4	Vdc
Gate Quiescent Voltage (V_{DS} = 27 Vdc, I_{DQ1A} = 0.35 µAdc)	$V_{GS(Q)}$	1.4	±0.4	Vdc
Fixture Gate Quiescent Voltage (V_{DD} = 27 Vdc, I_{DQ1A} = 0.35 µAdc, Measured in Functional Test)	$V_{GG(Q)}$	1.4	±0.4	Vdc
Peaking Stage 2 — On Characteristics (1)				
Gate Threshold Voltage (V_{DS} = 10 Vdc, I_D = 41 µAdc)	$V_{GS(th)}$	1.2	±0.4	Vdc
Gate Quiescent Voltage (V_{DS} = 27 Vdc, I_{DQ2A} = 0.35 µAdc)	$V_{GS(Q)}$	1.3	±0.4	Vdc
Fixture Gate Quiescent Voltage (V_{DD} = 27 Vdc, I_{DQ2A} = 0.35 µAdc, Measured in Functional Test)	$V_{GG(Q)}$	1.3	±0.4	Vdc

1. Each side of device measured separately.

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9.2 Functional tests

Table 8. Functional Tests — 2496 MHz (1)

(In NXP Doherty Production ATE (2) Test Fixture, T_A = 25°C unless otherwise noted, 50 ohm system) V_{DD} = 27 Vdc, I_{DQ1A} = 24 mA, I_{DQ2A} = 65 mA, V_{GS1B} = (V_t − 0.12) Vdc, V_{GS2B} = (V_t − 0.25) Vdc, P_{out} = 8 W Avg., 1−tone CW, f = 2496 MHz.

Characteristic	Symbol	Min	Typ	Max	Unit
Gain	G	27.0	28.2	—	dB
Drain Efficiency	η_D	38.0	45.5	—	%
P_{out} @ 3 dB Compression Point (Pulsed CW, 5% Duty Cycle)	P3dB	47.2	48.0	—	dBm

Table 9. Functional Tests — 2690 MHz (1)

(In NXP Doherty Production ATE (2) Test Fixture, T_A = 25°C unless otherwise noted, 50 ohm system) V_{DD} = 27 Vdc, I_{DQ1A} = 24 mA, I_{DQ2A} = 65 mA, V_{GS1B} = (V_t − 0.12) Vdc, V_{GS2B} = (V_t − 0.25) Vdc, P_{out} = 8 W Avg., 1−tone CW, f = 2690 MHz.

Characteristic	Symbol	Min	Typ	Max	Unit
Gain	G	26.5	28.0	—	dB
Drain Efficiency	η_D	36.0	41.9	—	%
P_{out} @ 3 dB Compression Point (Pulsed CW, 5% Duty Cycle)	P3dB	46.0	46.8	—	dBm

9.3 Wideband ruggedness

Table 10. Wideband Ruggedness (3)

(In NXP Doherty Power Amplifier Module Reference Circuit, T_A = 25°C unless otherwise noted, 50 ohm system) I_{DQ1A} = 23.5 mA, I_{DQ2A} = 64.5 mA, V_{GSP1} = 1.4 Vdc, V_{GSP2} = 1.25 Vdc, f = 2600 MHz, Additive White Gaussian Noise (AWGN) with 10 dB PAR

Characteristic	Test Results
ISBW of 400 MHz at 27 Vdc, 3 dB Input Overdrive from 8 W Avg. Modulated Output Power	No Device Degradation

1. Part input and output matched to 50 ohms.
2. ATE is a socketed test environment.
3. All data measured in fixture with device soldered in NXP reference circuit.

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9.4 Typical performance

Table 11. Typical Performance [1]

(In NXP Doherty Power Amplifier Module Reference Circuit, T_A = 25°C unless otherwise noted, 50 ohm system) V_{DD} = 27 Vdc, I_{DQ1A} = 23.5 mA, I_{DQ2A} = 64.5 mA, V_{GSP1} = 1.4 Vdc, V_{GSP2} = 1.25 Vdc, P_{out} = 8 W Avg., 2600 MHz

Characteristic	Symbol	Min	Typ	Max	Unit
VBW Resonance Point, 2–tone, 1 MHz Tone Spacing (IMD Third Order Intermodulation Inflection Point)	VBW_{res}	—	100	—	MHz
Quiescent Current Accuracy over Temperature [2] with 2.2 kΩ Gate Feed Resistors (–40 to 85°C) Stage 1 with 2.2 kΩ Gate Feed Resistors (–40 to 85°C) Stage 2	ΔI_{QT}	 — —	 1.2 8.6	 — —	%
1–carrier 20 MHz LTE, 8 dB Input Signal PAR					
Gain	G	—	29.6	—	dB
Power Added Efficiency	PAE	—	41.8	—	%
Adjacent Channel Power Ratio	ACPR	—	–28.0	—	dBc
Adjacent Channel Power Ratio	ALT1	—	–42.1	—	dBc
Adjacent Channel Power Ratio	ALT2	—	–51.0	—	dBc
Gain Flatness [3]	G_F	—	±0.5	—	dB
Fast CW, 27 ms Sweep					
P_{out} @ 3 dB Compression Point	P3dB	—	47.1	—	dBm
AM/PM @ P3dB	Φ	—	–30	—	°
Gain Variation @ Avg. Power over Temperature (–40°C to +105°C)	ΔG	—	0.045	—	dB/°C
P3dB Variation over Temperature (–40°C to +105°C)	ΔP3dB	—	0.03	—	dB/°C

10 Ordering information

Table 12. Ordering Information

Device	Tape and Reel Information	Package
AFSC5G26E39T2	T2 Suffix = 2000 Units, 24 mm Tape Width, 13–inch Reel	10 mm × 6 mm Module

1. All data measured in fixture with device soldered in NXP reference circuit.
2. Refer to AN1977, *Quiescent Current Thermal Tracking Circuit in the RF Integrated Circuit Family*, and to AN1987, *Quiescent Current Control for the RF Integrated Circuit Device Family*. Go to http://www.nxp.com/RF and search for AN1977 or AN1987.
3. Gain flatness = Max(G(f_{Low} to f_{High})) – Min(G(f_{Low} to f_{High}))

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11 Component layout and parts list

11.1 Component layout

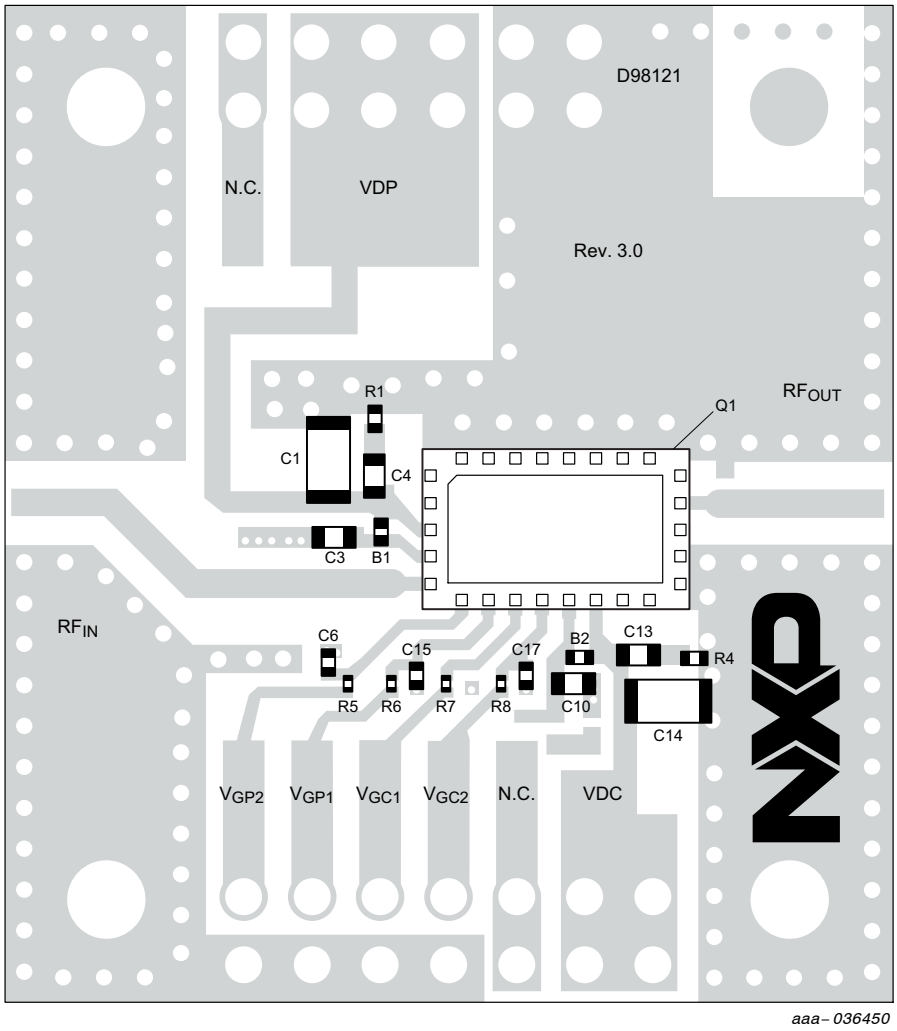


Figure 2. AFSC5G26E39 Reference Circuit Component Layout

11.2 Component designations and values

Table 13. AFSC5G26E39 Reference Circuit Component Designations and Values

Part	Description	Part Number	Manufacturer
B1, B2	30 Ω Ferrite Bead	BLM15PD300SN1	Murata
C1, C14	10 µF Chip Capacitor	CL31A106KBHNNNE	Samsung
C3, C4, C10, C13	1 µF Chip Capacitor	06035D105KAT2A	AVX
C6, C15, C17	0.1 µF Chip Capacitor	GRM155R61H104KE14	Murata
Q1	Power Amplifier Module	AFSC5G26E39	NXP
R1, R4	5.1 Ω, 1/10 W Chip Resistor	ERJ-2GEJ5R1X	Panasonic
R5, R6, R7, R8	2.2 kΩ, 1/20 W Chip Resistor	ERJ-1GNJ222C	Panasonic
PCB	Rogers RO4350B, 0.020″, ε_r = 3.66	D98121	MTL

Note: Component numbers C2, C5, C7, C8, C9, C11, C12, C16, R2 and R3 are intentionally omitted.

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12 Product marking



Figure 3. Product Marking

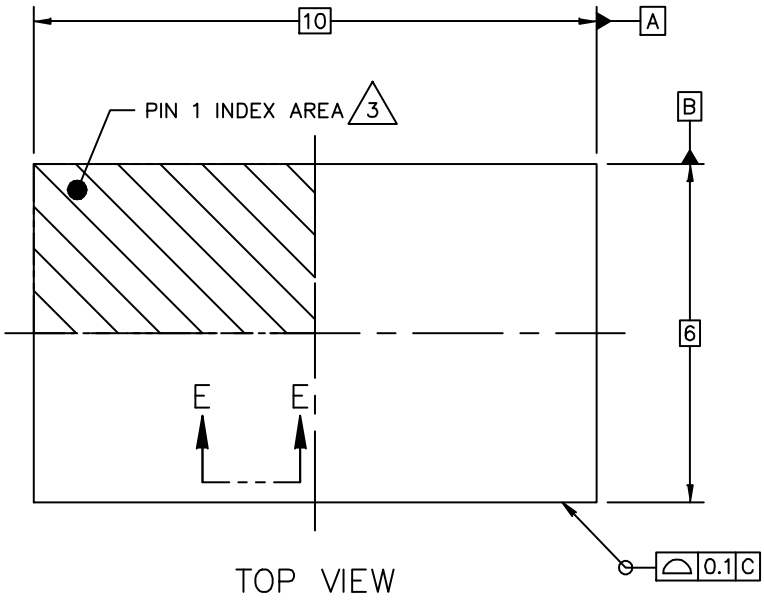
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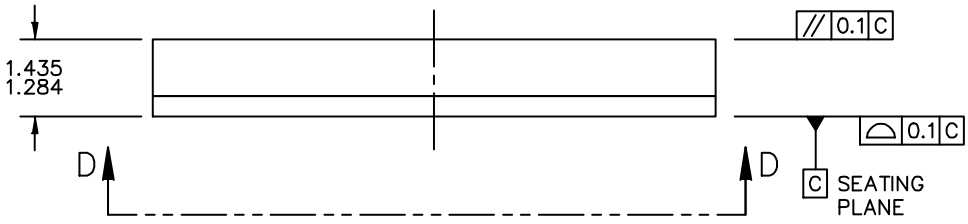
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13 Package information

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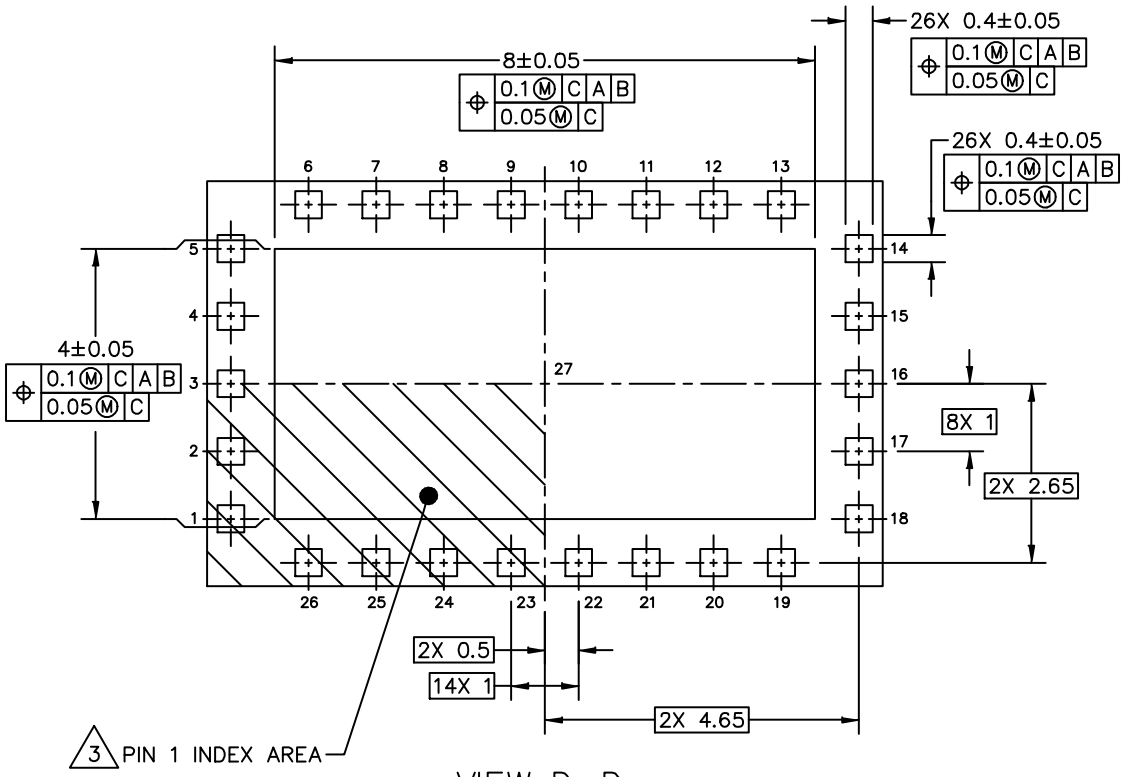
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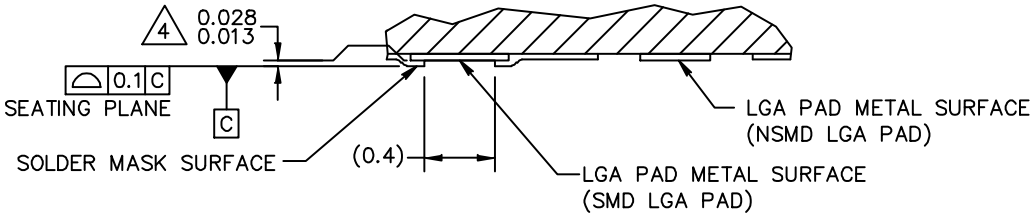
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VIEW D-D
(BOTTOM VIEW)



SECTION E-E 5

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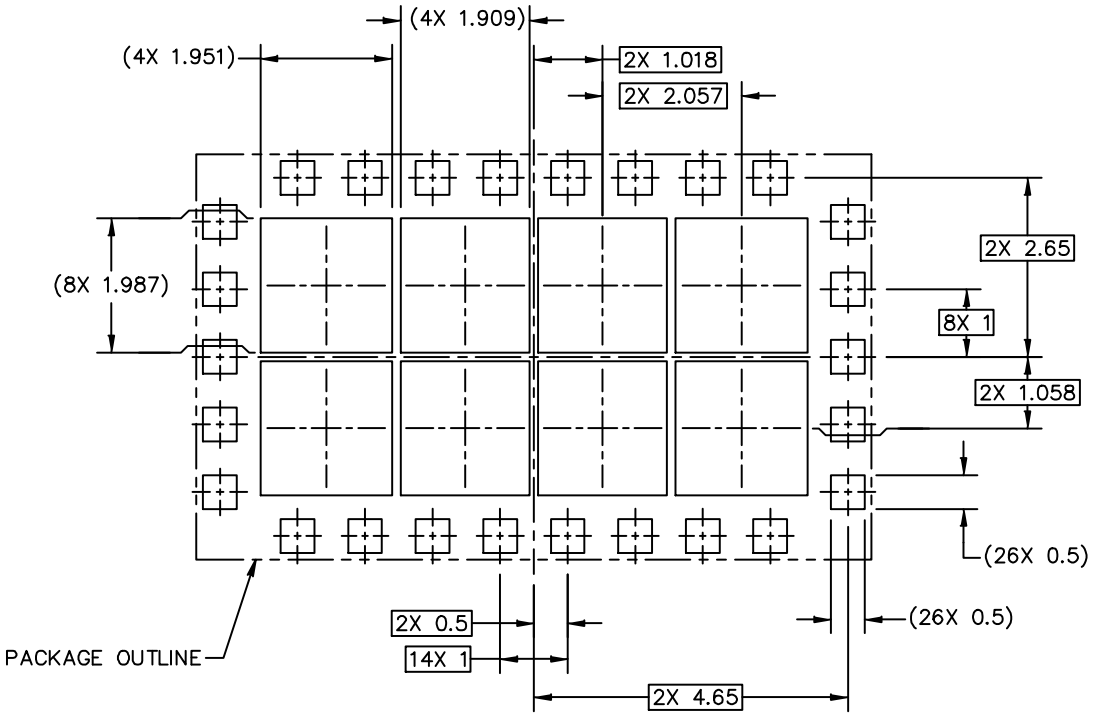
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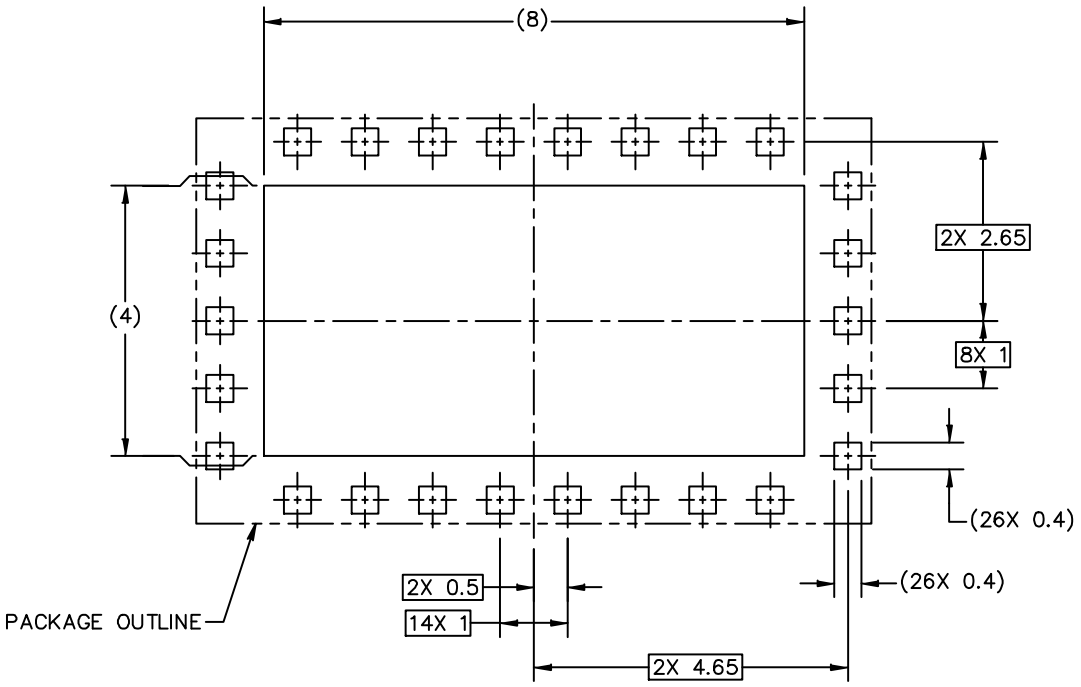
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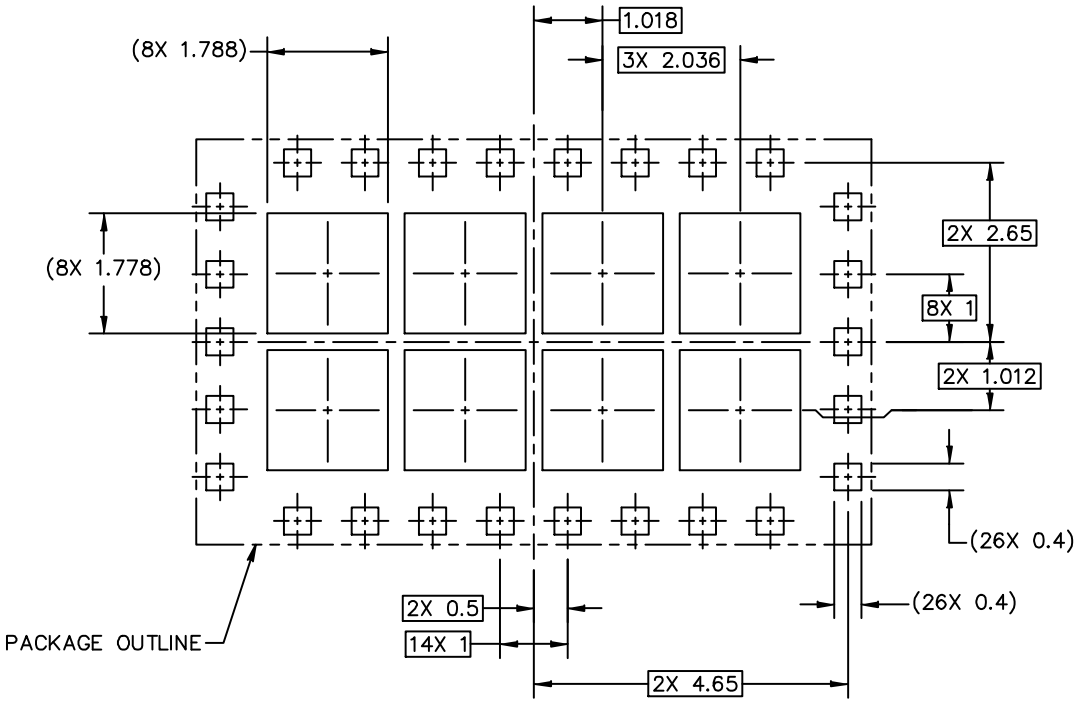
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RECOMMENDED STENCIL THICKNESS 0.125

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DIMENSION APPLIES TO ALL LEADS AND FLAG.
5. THE BOTTOM VIEW SHOWS THE SOLDERABLE AREA OF THE PADS. THE CENTER PAD (PIN 27) IS SOLDER MASK DEFINED. SOME PERIPHERAL PADS ARE SOLDER MASK DEFINED (SMD) AND OTHERS ARE NON–SOLDERMASK DEFINED (NSMD).

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14 Product documentation and tools

Refer to the following resources to aid your design process.

Application Notes

- AN1977: Quiescent Current Thermal Tracking Circuit in the RF Integrated Circuit Family
- AN1987: Quiescent Current Control for the RF Integrated Circuit Device Family

Development Tools

- Printed Circuit Boards

15 Failure analysis

At this time, because of the physical characteristics of the part, failure analysis is limited to electrical signature analysis. In cases where NXP is contractually obligated to perform failure analysis (FA) services, full FA may be performed by third party vendors with moderate success. For updates contact your local NXP Sales Office.

16 Revision history

The following table summarizes revisions to this document.

Table 14. Revision History

Document ID	Release Date	Description
AFSC5G26E39 Rev. 2	14 June 2024	• Tables 8 and 9, Functional Tests, 2496 MHz and 2690 MHz: updated output power test condition, p. 6
AFSC5G26E39 Rev. 1	30 September 2020	• Table 8, Test Circuit Component Designations and Values: updated R5, R6, R7, R8 part number ERJ−1GEJ222C (discontinued) to ERJ−1GNJ222C (replacement component), p. 7 • General updates made to align data sheet to current standard
AFSC5G26E39 Rev. 0	5 February 2020	• Initial release of product data sheet

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Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term 'short data sheet' is explained in section "Definitions".
[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL https://www.nxp.com.

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